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MANUFACTURING METHOD OF
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ABSTRACT

A manufacturing apparatus of a semiconductor device includes a stage, a mounting tool, a pressing mechanism, and a controller. The pressing mechanism moves the mounting tool in a vertical direction and applies a load to a chip. The controller is configured to perform a first process and a detection process. In the first process, after bringing the chip into contact and until a bump melts, the chip is heated by the mounting tool and a command position of the pressing mechanism is constantly updated so that a positional deviation is constant. In the detection process, melting of the bump is detected based on a decrease in the pressing load.

